# OUPONT

# DuPont<sup>™</sup> Kapton<sup>®</sup> HN

Polyimide Film

# Description

DuPont<sup>™</sup> Kapton<sup>®</sup> HN general-purpose film has been used successfully in applications at temperatures as low as -269°C (-452°F) and as high as 400°C (752°F). HN film can be laminated, metallized, punched, formed or adhesive coated. Kapton<sup>®</sup> HN is the recommended choice for applications that require an all-polyimide film with an excellent balance of properties over a wide range of temperatures.

## Applications

- Mechanical parts
- Electronic parts
- Electrical Insulation
- Pressure sensitive tape

- Fiber optics cable
- Insulation blankets
- Insulation tubing
- · Automotive diaphragms sensors and manifolds
- Etching
- Shims

## **Product Specifications**

Kapton<sup>®</sup> HN is manufactured, slit and packaged according to the product specifications listed in H-38479 (6/18).

#### Certification

Kapton® HN meets ASTM D-5213 (type 1, item A) requirements.

Property	Unit	.05 mil 12.7µm	1 mil 25µm	2 mil 50µm	3 mil 75µm	5 mil 125µm	Test Method
Ultimate Tensile Strength at 23°C, (73°F) at 200°C (392°F)	psi (MPa)	33,500 (231) 20,000 (138)	33,500 (231) 20,000 (138)	33,500 (231) 20,000 (138)	33,500 (231) 20,000 (138)	33,500 (231) 20,000 (138)	ASTM D-882-91, Method A*
Ultimate Elongation at 23°C, (73°F) at 200°C (392°F)	%	65 68	72 83	72 83	78 83	82 83	ASTM D-882-91, Method A
Tensile Modulus at 23°C, (73°F) at 200°C (392°F)	psi (GPa)	400,000 (2.76) 160,000 (1.10)	400,000 (2.76) 290,000 (2.0)	400,000 (2.76) 290,000 (2.0)	400,000 (2.76) 290,000 (2.0)	400,000 (2.76) 290,000 (2.0)	ASTM D-882-91, Method A
Density	g/cc	1.42	1.42	1.42	1.42	1.42	ASTM D-1505-90
MIT Folding Endurance	cycles	>285,000	285,000	55,000	6,000	5,000	ASTM D-2176-89
Tear Strength-propagating (Elmendorf), N (lbf)		NA	0.07 (0.02)	0.21 (0.02)	0.38 (0.02)	0.58 (0.02)	ASTM D-1922-89
Tear Strength, Initial (Graves), N (lbf)		3.5 (1.6)	7.2 (1.6)	16.3 (1.6)	26.3 (1.6)	46.9 (1.6)	ASTM D-1004-90
Yield Point at 3% at 23°C, (73°F) at 200°C (392°F)	MPa (psi)	69 (10,000) 41 (6,000)	69 (10,000) 41 (6,000)	69 (10,000) 41 (6,000)	69 (10,000) 41 (6,000)	69 (10,000) 41 (6,000)	ASTM D-882-91
Stress to produce 5% elong. at 23°C, (73°F) at 200°C (392°F)	MPa (psi)	90 (13,000) 62 (9,000)	90 (13,000) 62 (9,000)	90 (13,000) 62 (9,000)	90 (13,000) 62 (9,000)	90 (13,000) 62 (9,000)	ASTM D-882-92
Impact Strength at 23°C, (73°F)	N· cm· (ft lb)	78 (0.58)	78 (0.58)	78 (0.58)	78 (0.58)	78 (0.58)	DuPont Pneumatic Impact Test
Coefficient of Friction, kinetic (film-to-film)		0.48	0.48	0.48	0.48	0.48	ASTM D-1894-90
Coefficient of Friction, static (film-to-film)		0.63	0.63	0.63	0.63	0.63	ASTM D-1894-90
Refractive Index (sodium D line)		1.70	1.70	1.70	1.70	1.70	ASTM D-542-90
Poisson's Ratio		0.34	0.34	0.34	0.34	0.34	Avg. three samples, elongated at 5, 7, 10%
Low temperature flex life		pass	pass	pass	pass	pass	IPC-TM-650, Method 2.6.18

Table 1 – Physical Properties of DuPont<sup>™</sup> Kapton<sup>®</sup> HN at 23°C (73°F)

\*Specimen size 25 x 150 mm (1.6 in); jaw separation 100 mm (4 in), jaw speed, 50mm/min (2 in/min). Ultimate refers to the tensile strength and elongation measured at break.

# Table 2 – Thermal Properties of DuPont<sup>™</sup> Kapton<sup>®</sup> HN Film

Thermal Property	Typical Value	Test Condition	Test Method
Melting Point	None	None	ASTM E-794-85 (1989)
Thermal Coefficient of Linear Expansion	20 ppm/°C (11 ppm/°F)	-14 to 38°C (7 to 100°F)	ASTM D-696-91
Coefficient of Thermal Conductivity, W/m· K (cal/sec-cm-°C)	0.20 (4.8 × 10 <sup>-4</sup> )	296 K (23°C)	ASTM D5470
Specific Heat, J/g•K (cal/g· °C)	1.09 (0.261)		Differential calorimetry
Heat Sealability	not heat sealable		
Solder Float	pass		IPC-TM-650 Method 2.4.13A
Smoke Generation	D <sub>m</sub> =<1	NBS smoke chamber	NFPA-258
Shrinkage, % 30 min at 150°C 120 min at 400°C	0.17 1.25		IPC-TM-650 Method 2.2.4A; ASTM D-5214-91
Limiting Oxygen Index, %	37-45		ASTM D-2863-87
Glass Transition Temperature (Tg)	A second order transition occurs in Kapton® between 360°C (680°F) and 410°C (770°F) and is assumed to be the glass transition temperature. Different measurement techniques produce different results within the above temperature range.		

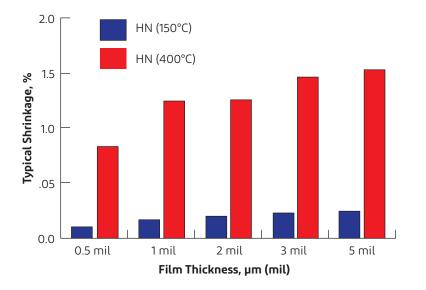
# Table 3 – Typical Electrical Properties of DuPont<sup>™</sup> Kapton<sup>®</sup> HN Film at 23°C (73°F), 50% RH

Property Film Gage	Typical Value		Test Condition	Test Method
Dielectric Strength 12.7 μm (0.5 mil) 25 μm (1 mil) 50 μm (2 mil) 75 μm (3 mil) 125 μm (5 mil)	V/um kV/mm 315 303 240 201 154	(V/mil) (8000) (7700) (6100) (5100) (3900)	60 Hz 1/4 in electrodes 500 V/sec rise	ASTM D-149-91
Dielectric Constant 12.7 μm (0.5 mil) 25 μm (1 mil) 50 μm (2 mil) 75 μm (3 mil) 125 μm (5 mil)	3.4 3.4 3.4 3.5 3.5		1 kHz	ASTM D-150-92
Dissipation Factor 12.7 μm (0.5 mil) 25 μm (1 mil) 50 μm (2 mil) 75 μm (3 mil) 125 μm (5 mil)	0.0016 0.0018 0.0020 0.0020 0.0026		1 kHz	ASTM D-150-92
Volume Resistivity 12.7 μm (0.5 mil) 25 μm (1 mil) 50 μm (2 mil) 75 μm (3 mil) 125 μm (5 mil)	Ω·cπ 1.5 x 1 1.5 x 1 1.5 x 1 1.4 x 1 1.0 x 1	0 <sup>17</sup> 0 <sup>17</sup> 0 <sup>17</sup> 0 <sup>17</sup>		ASTM D-257-91

#### **Dimensional Stability**

The dimensional stability of DuPont<sup>™</sup> Kapton<sup>®</sup> polyimide film depends on two factorsthe normal coefficient of thermal expansion and the residual stresses placed in the film during manufacture. The latter causes Kapton® to shrink on its first exposure to elevated temperatures as indicated in the bar graph in Figure 1. Once the film has been exposed, the normal values of the thermal coefficient of linear expansion as shown in **Table 4** can be expected.





#### Table 4 – Thermal Coefficient of Expansion, DuPont<sup>™</sup> Kapton<sup>®</sup> HN Film, 25 µm (1 mil), Thermally Exposed

Temperature Range, °C, (°F)	ppm/°C
30–100 (86–212)	17
100–200 (212–392)	32
200–300 (392–572)	40
300-400 (572-752)	44
30-400 (86-752)	34



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# For more information on DuPont<sup>™</sup> Kapton<sup>®</sup> or other DuPont products, please visit our website.

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